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Inform ECN Overview Production Process Fujitsu Mainboards

ECN-No. BSA 1-2015

Reason for ECN: Change in wave soldering process

without any impact on mainboard form, fit and function.

Shipping details: Shipment of mainboards manufactured with new process will be a running change,

expected to start mid of July 2015.

Mainboards in general:

Change in the wave soldering process: Replacement of CuSn solder by BiSnAg solder	Mainboard	Version	Features	Reason for ECN	ECN Date
All All Better hole fill for through hole components (IPC-A-610E) Reduction of thermal stress for all components Less board warpage due to production process	All	All		 Replacement of CuSn solder by BiSnAg solder Better hole fill for through hole components (IPC-A-610E) Reduction of thermal stress for all components 	07/2015

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